



Parameter	Rating	Units
Blocking Voltage	600	V <sub>P</sub>
Load Current	90	mA <sub>rms</sub> / mA <sub>DC</sub>
On-Resistance (max)	50	Ω

## Features

- 5000V<sub>rms</sub> Input/Output Isolation
- 600V<sub>P</sub> Blocking Voltage
- 100% Solid State
- Low Drive Power Requirements (TTL/CMOS Compatible)
- Arc-Free With No Snubbing Circuits
- No EMI/RFI Generation
- Small 4-Pin Package
- Machine Insertable, Wave Solderable

## Applications

- Instrumentation
  - Multiplexers
  - Data Acquisition
  - Electronic Switching
  - I/O Subsystems
- Meters (Watt-Hour, Water, Gas)
- Medical Equipment—Patient/Equipment Isolation
- Security
- Aerospace
- Industrial Controls

## Description

The CPC1393G is a single-pole, normally open (1-Form-A) Solid State Relay with an enhanced input to output isolation barrier of 5000V<sub>rms</sub>.

The relay output is constructed with efficient MOSFET switches that use IXYS Integrated Circuits Division's patented OptoMOS architecture. The input, a highly efficient GaAlAs infrared LED, controls the optically coupled output.

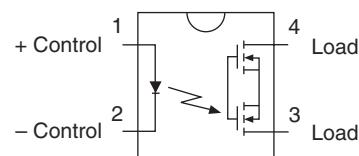
## Approvals

- UL Certified Component: File E76270
- CSA Certified Component: Certificate 1172007
- EN/IEC 60950-1 Certified Component: TUV Certificate B 10 05 49410 006

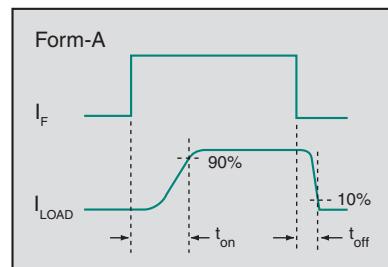
## Ordering Information

Part Number	Description
CPC1393G	4-Pin DIP (100/Tube)
CPC1393GV	4-Pin DIP V-Bend (100/Tube)
CPC1393GR	4-Pin Surface Mount (100/Tube)
CPC1393GRTR	4-Pin Surface Mount (1000/Reel)

## Pin Configuration



## Switching Characteristics of Normally Open Devices



## Absolute Maximum Ratings @ 25°C

Parameter	Ratings	Units
Peak Blocking Voltage	600	V <sub>P</sub>
Reverse Input Voltage	5	V
Input Control Current Peak (10ms)	50	mA
	1	A
Input Power Dissipation <sup>1</sup>	100	mW
Total Package Dissipation <sup>2</sup>	550	mW
Isolation Voltage, Input to Output	5000	V <sub>rms</sub>
Operational Temperature	-40 to +85	°C
Storage Temperature	-40 to +125	°C

<sup>1</sup> Derate linearly 1.33 mW / °C

<sup>2</sup> Derate linearly 3.00 mW / °C

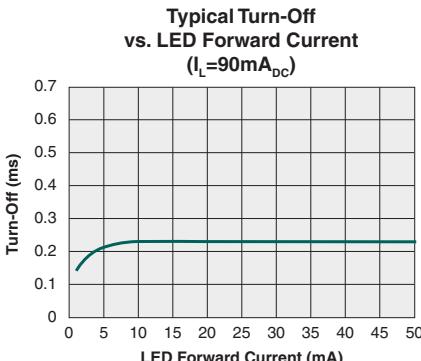
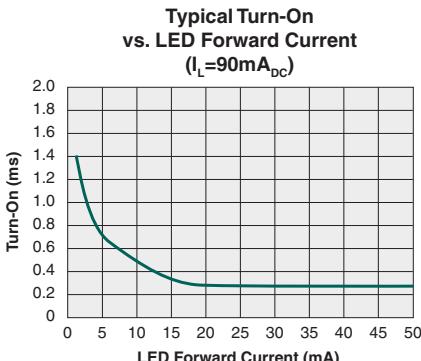
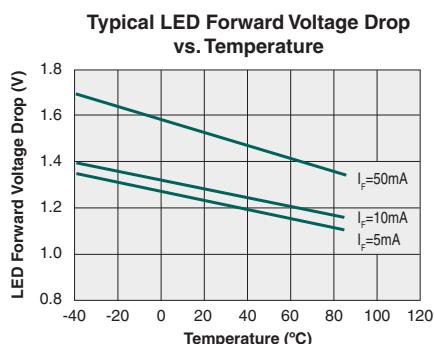
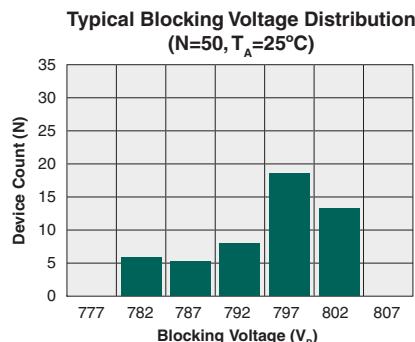
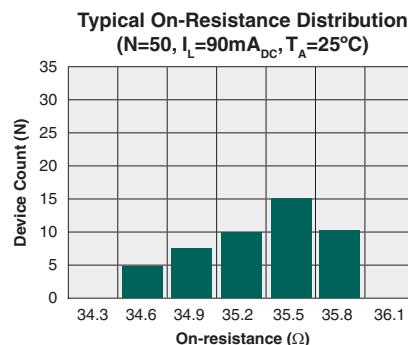
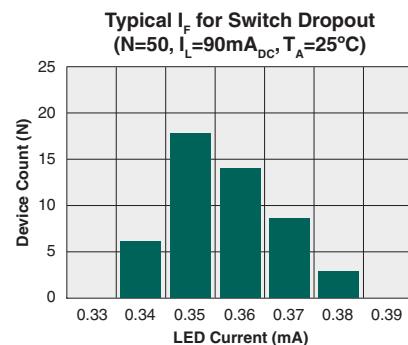
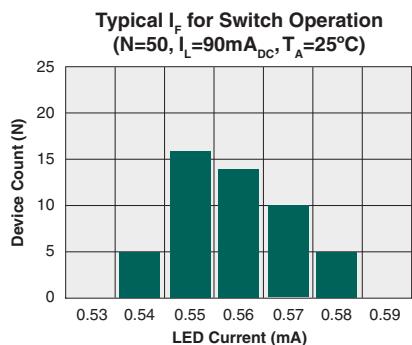
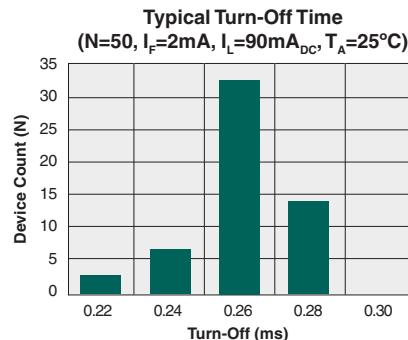
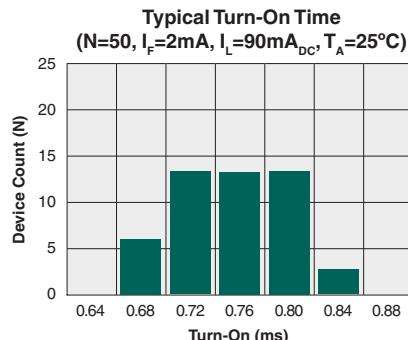
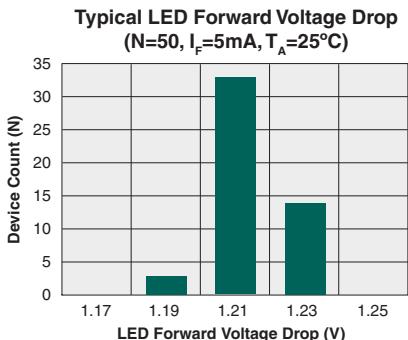
*Absolute Maximum Ratings are stress ratings. Stresses in excess of these ratings can cause permanent damage to the device. Functional operation of the device at conditions beyond those indicated in the operational sections of this data sheet is not implied.*

## Electrical Characteristics @ 25°C

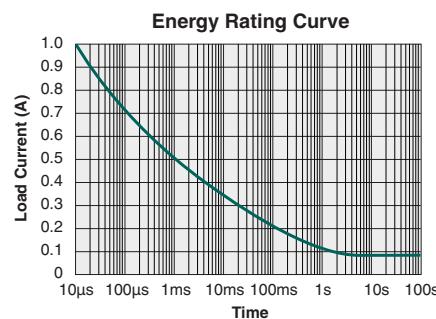
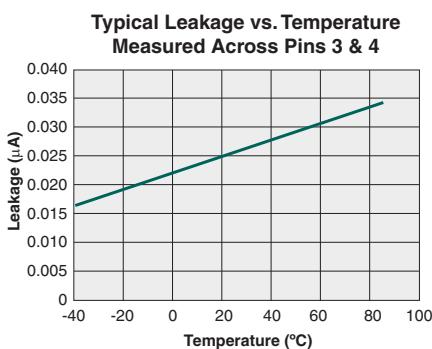
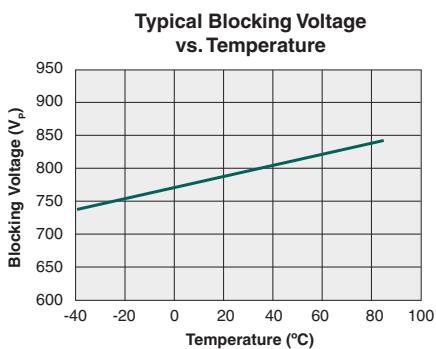
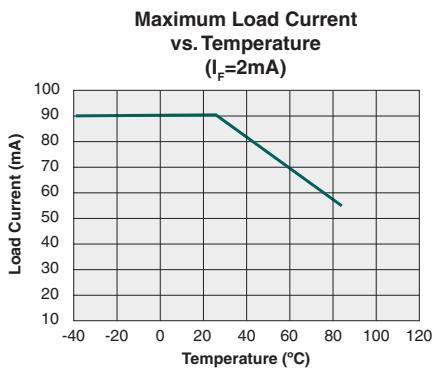
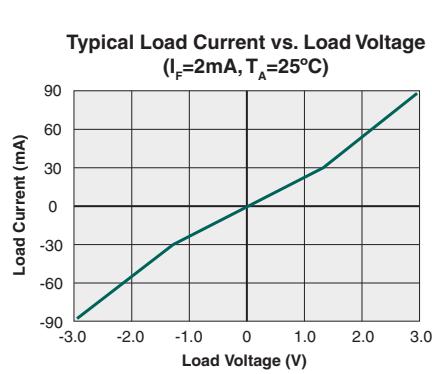
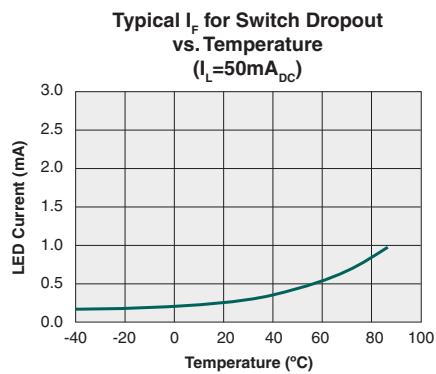
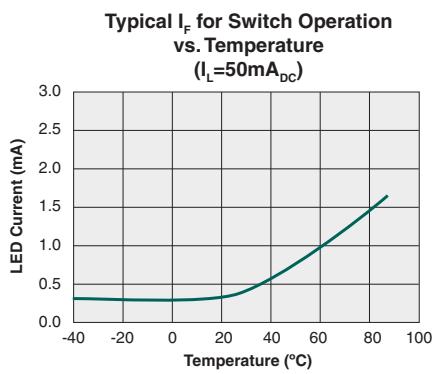
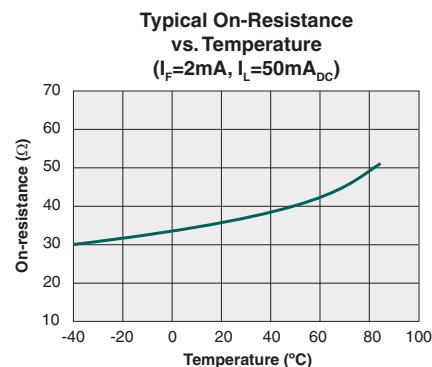
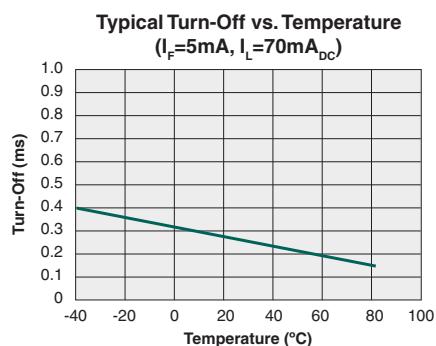
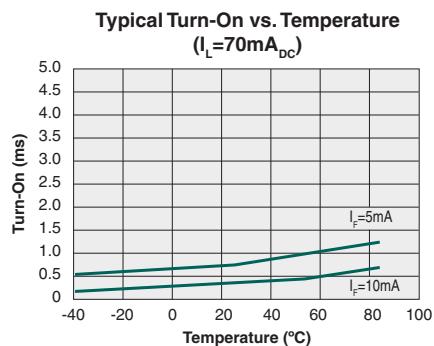
Parameters	Conditions	Symbol	Min	Typ	Max	Units
<b>Output Characteristics</b>						
Load Current						
Continuous	-	I <sub>L</sub>	-	-	90	mA <sub>rms</sub> / mA <sub>DC</sub>
Peak	t=10ms	I <sub>LPK</sub>	-	-	±350	mA <sub>P</sub>
On-Resistance <sup>1</sup>	I <sub>L</sub> =90mA	R <sub>ON</sub>	-	35	50	Ω
Off-State Leakage Current	V <sub>L</sub> =600V <sub>P</sub>	I <sub>LEAK</sub>	-	-	1	μA
Switching Speeds						
Turn-On	I <sub>F</sub> =5mA, V <sub>L</sub> =10V	t <sub>on</sub>	-	-	5	ms
Turn-Off		t <sub>off</sub>	-	-	5	
Output Capacitance	I <sub>F</sub> =0mA, V <sub>L</sub> =50V, f=1MHz	C <sub>OUT</sub>	-	50	-	pF
<b>Input Characteristics</b>						
Input Control Current to Activate	I <sub>L</sub> =90mA	I <sub>F</sub>	-	0.55	2	mA
Input Control Current to Deactivate	-	I <sub>F</sub>	0.2	-	-	
Input Voltage Drop	I <sub>F</sub> =5mA	V <sub>F</sub>	0.9	1.2	1.4	V
Reverse Input Current	V <sub>R</sub> =5V	I <sub>R</sub>	-	-	10	μA
<b>Common Characteristics</b>						
Input to Output Capacitance	-	C <sub>I/O</sub>	-	3	-	pF

<sup>1</sup> Measurement taken within 1 second of on-time.

## PERFORMANCE DATA\*



\*The Performance data shown in the graphs above is typical of device performance. For guaranteed parameters not indicated in the written specifications, please contact our application department.

**PERFORMANCE DATA\***


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## Manufacturing Information

### Moisture Sensitivity

 All plastic encapsulated semiconductor packages are susceptible to moisture ingress. IXYS Integrated Circuits Division classified all of its plastic encapsulated devices for moisture sensitivity according to the latest version of the joint industry standard, **IPC/JEDEC J-STD-020**, in force at the time of product evaluation. We test all of our products to the maximum conditions set forth in the standard, and guarantee proper operation of our devices when handled according to the limitations and information in that standard as well as to any limitations set forth in the information or standards referenced below.

Failure to adhere to the warnings or limitations as established by the listed specifications could result in reduced product performance, reduction of operable life, and/or reduction of overall reliability.

This product carries a **Moisture Sensitivity Level (MSL) rating** as shown below, and should be handled according to the requirements of the latest version of the joint industry standard **IPC/JEDEC J-STD-033**.

Device	Moisture Sensitivity Level (MSL) Rating
CPC1393G / CPC1393GV / CPC1393GR	MSL 1

### ESD Sensitivity



This product is **ESD Sensitive**, and should be handled according to the industry standard **JESD-625**.

### Reflow Profile

This product has a maximum body temperature and time rating as shown below. All other guidelines of **J-STD-020** must be observed.

Device	Maximum Temperature x Time
CPC1393G / CPC1393GV / CPC1393GR	250°C for 30 seconds

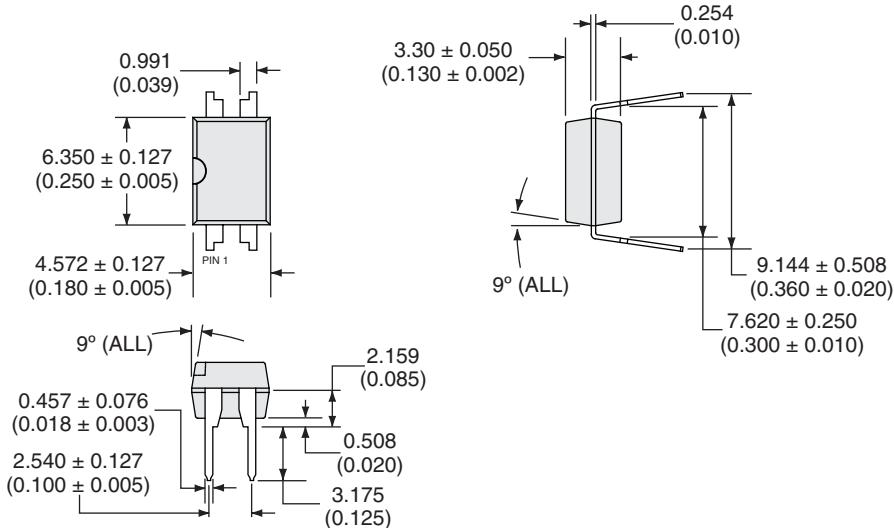
### Board Wash

IXYS Integrated Circuits Division recommends the use of no-clean flux formulations. However, board washing to remove flux residue is acceptable. Since IXYS Integrated Circuits Division employs the use of silicone coating as an optical waveguide in many of its optically isolated products, the use of a short drying bake could be necessary if a wash is used after solder reflow processes. Chlorine- or Fluorine-based solvents or fluxes should not be used. Cleaning methods that employ ultrasonic energy should not be used.

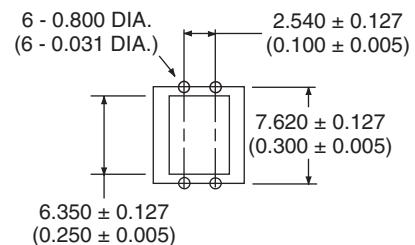


## MECHANICAL DIMENSIONS

### CPC1393G

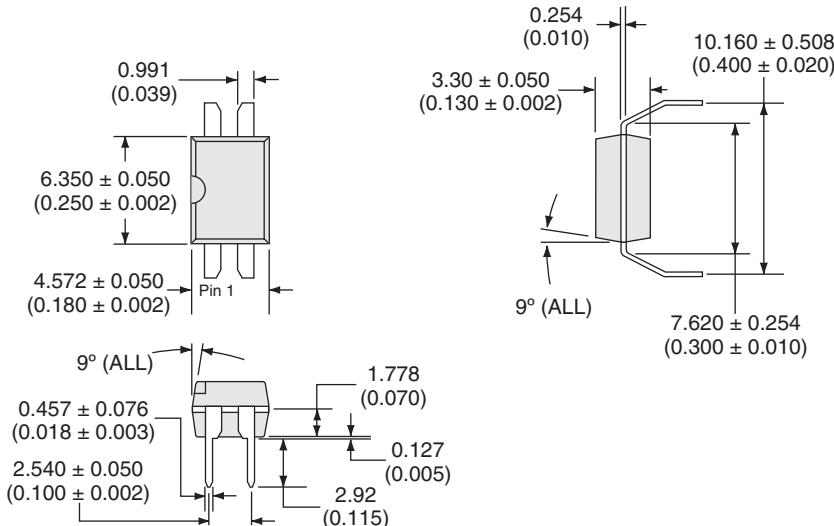


### PC Board Pattern (Top View)

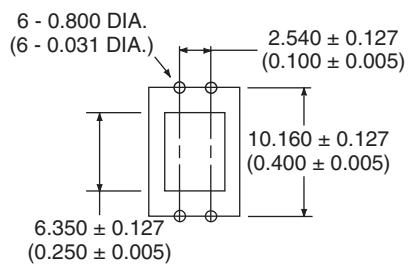


Dimensions  
mm  
(inches)

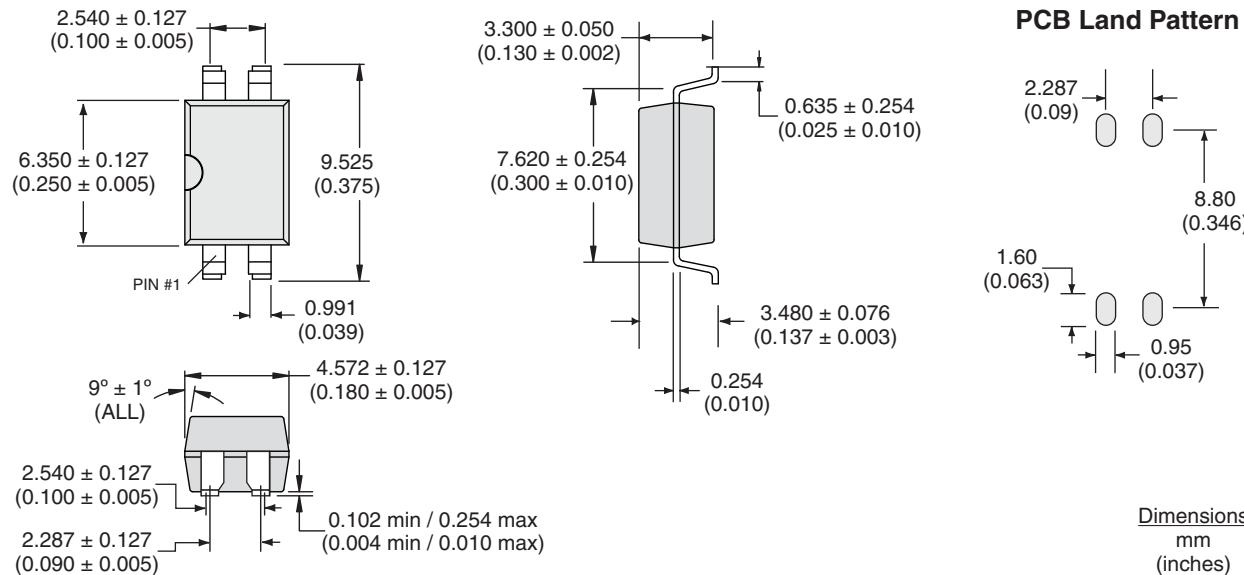
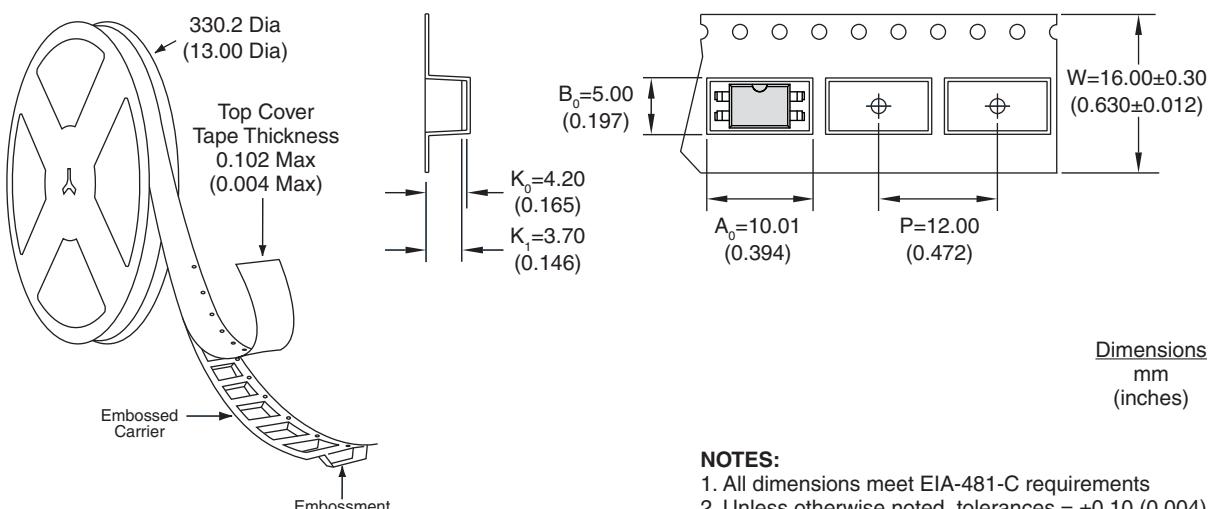
### CPC1393GV



### PC Board Pattern (Top View)



Dimensions  
mm  
(inches)

**CPC1393GR**

**CPC1393GRTR Tape & Reel**

**NOTES:**

1. All dimensions meet EIA-481-C requirements
2. Unless otherwise noted, tolerances = ±0.10 (0.004)

For additional information please visit our website at: [www.ixysic.com](http://www.ixysic.com)

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